

09/762582

JCO5 Rec'd PCT/PTO 09 FEB 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :

Akihisa HONGO et al. :

Attn: BOX PCT

Serial No. ~~NEW~~ 09/762582 :

Docket No. 2001_0133A

Filed February 9, 2001 :

SUBSTRATE PLATING METHOD AND APPARATUS
[Corresponding to PCT/JP99/04349
Filed August 11, 1999]

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

SAD
#SA
6-6-01

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

Prior to initial examination of the above-identified
application, kindly amend the application as follows:

IN THE CLAIMS:

Kindly amend claims 3, ~~5~~ 6, 8 and 11 as follows:

A1 3[AMENDED] A method or apparatus for plating a substrate
according to claim 1, comprising in said electroless plating
process or said electroless plating bath:

means for disposing a substrate to be plated in such a
state that a surface to be processed thereof faces upwardly, and
forming a hermetically sealed space by said surface to be
processed; and

Attachment "D"